



SOT618-16(SC)

HVQFN40, thermal enhanced very thin quad flat package; no leads; step-cut wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

3 April 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	07-03-2019
Manufacturer package code	98ASA01396D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
seated height	-	0.8	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



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2 Package outline

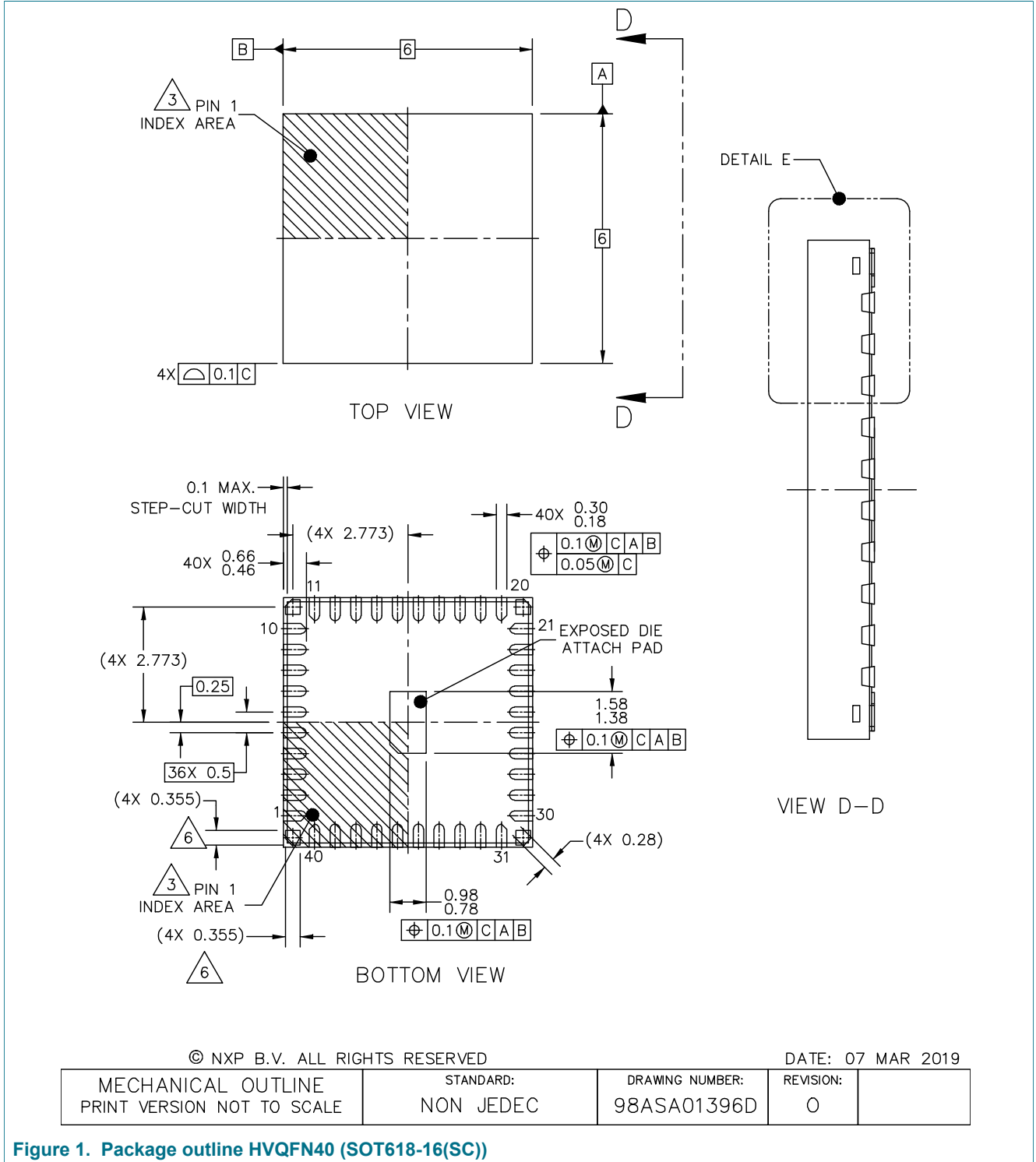


Figure 1. Package outline HVQFN40 (SOT618-16(SC))

HVQFN40, thermal enhanced very thin quad flat package; no leads; step-cut wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

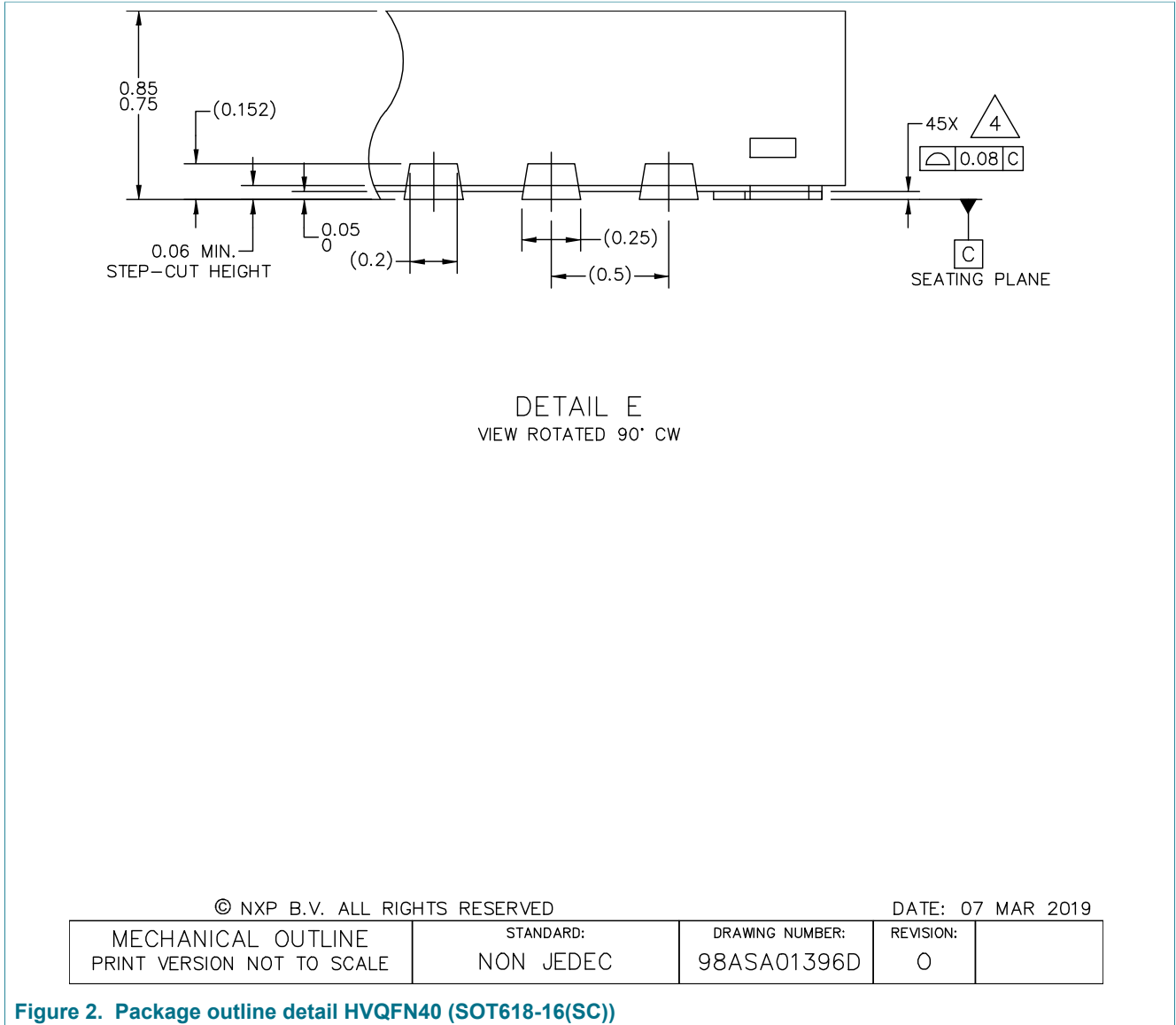


Figure 2. Package outline detail HVQFN40 (SOT618-16(SC))

HVQFN40, thermal enhanced very thin quad flat package; no leads; step-cut wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

3 Soldering

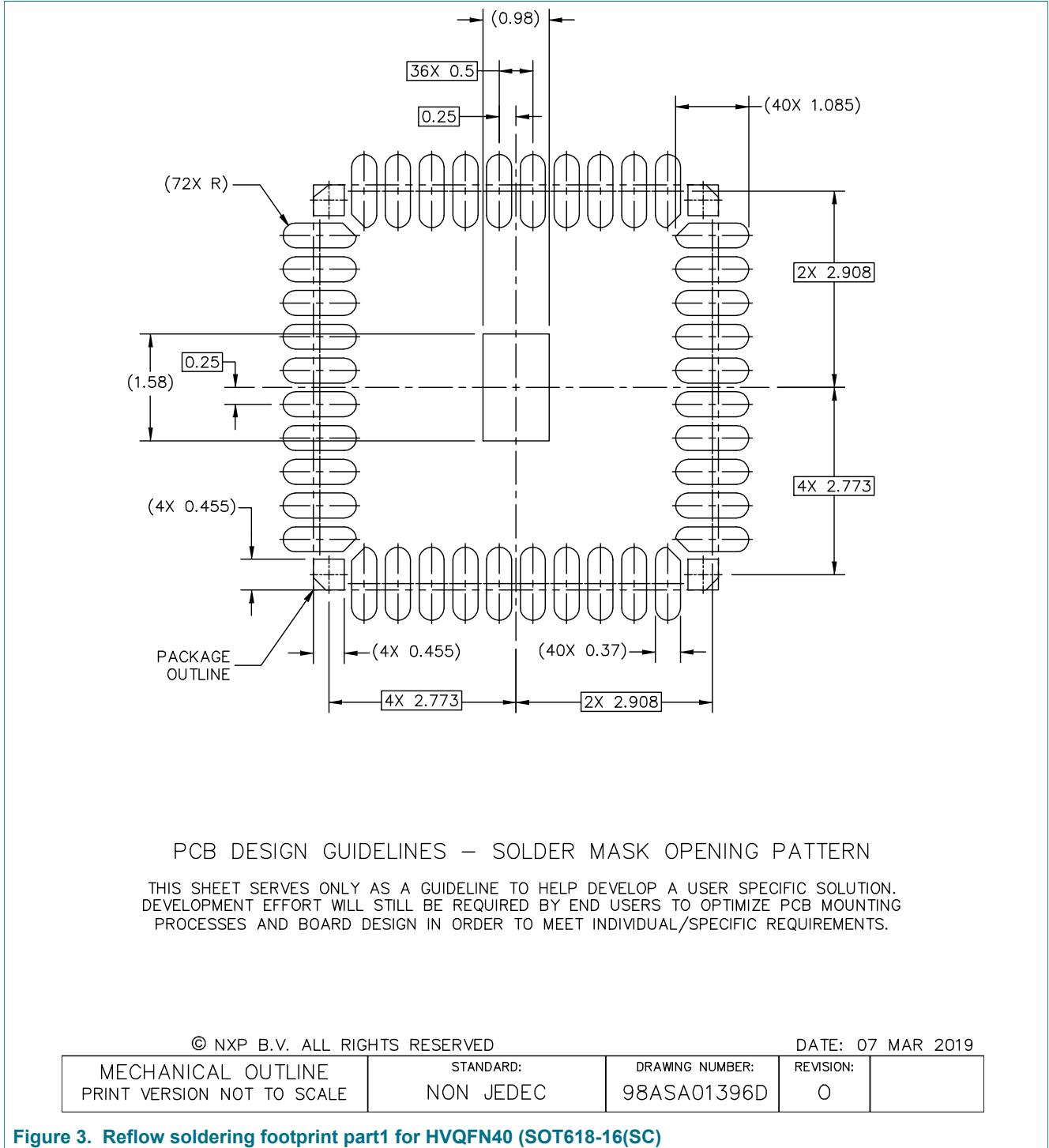
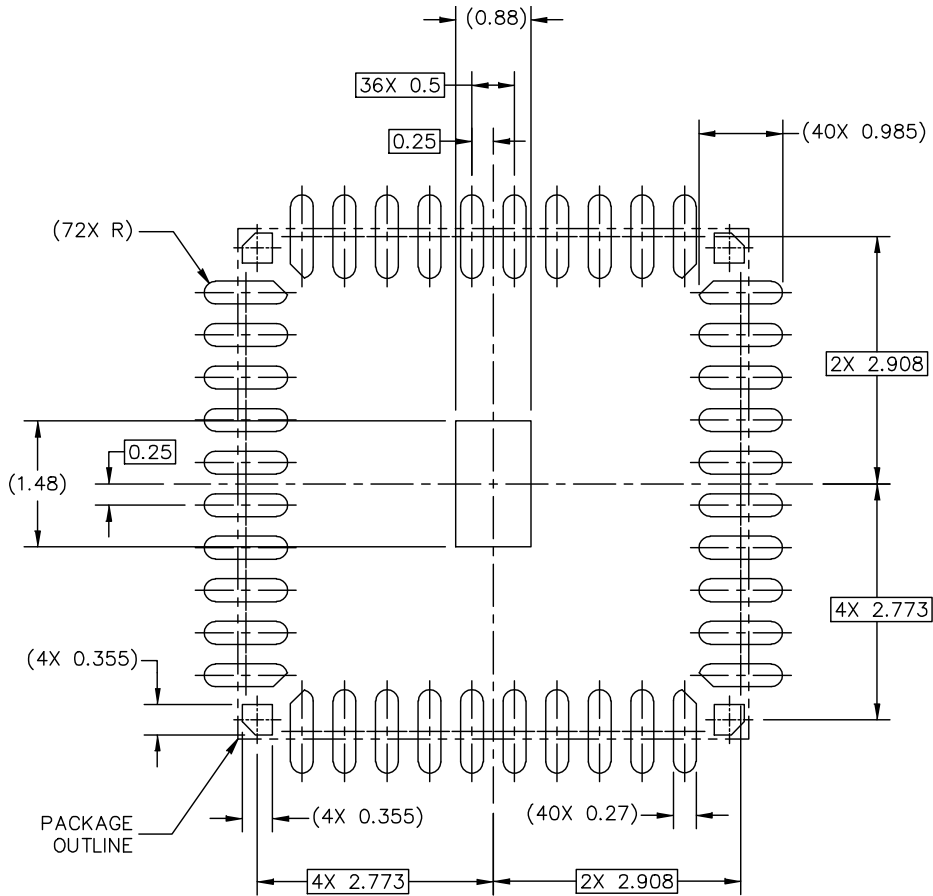


Figure 3. Reflow soldering footprint part1 for HVQFN40 (SOT618-16(SC))

HVQFN40, thermal enhanced very thin quad flat package; no leads; step-cut wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body



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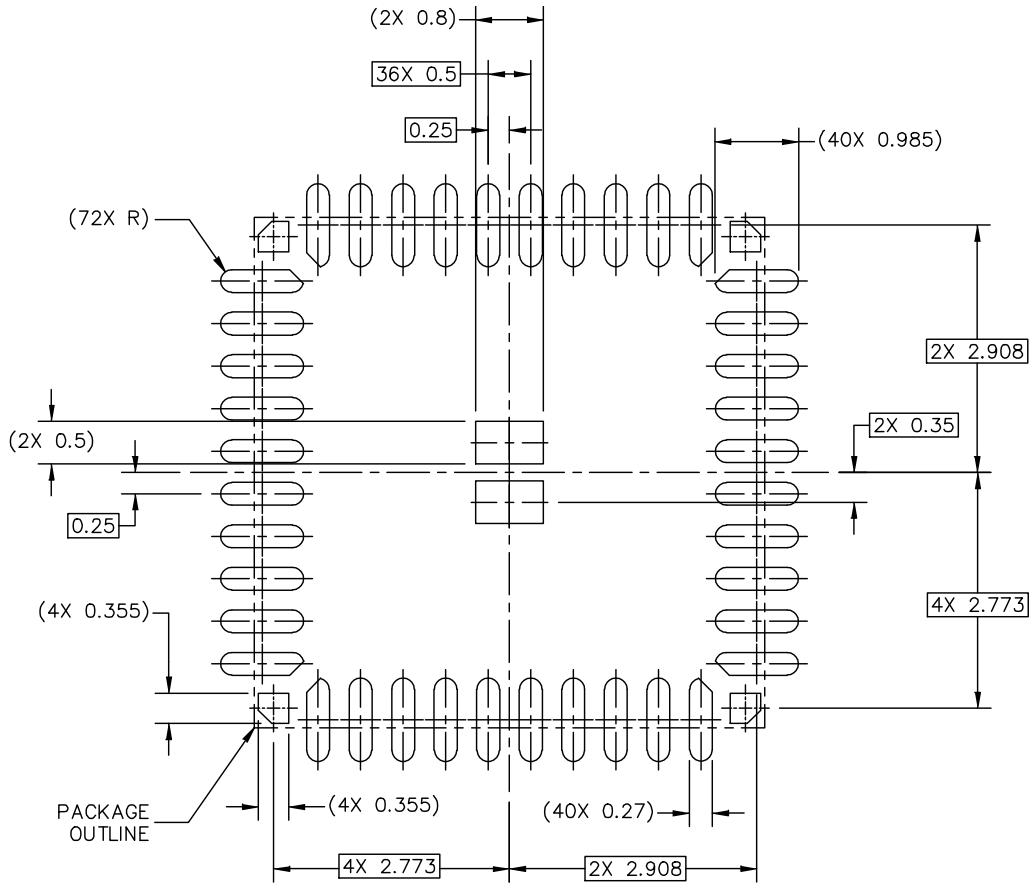
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Figure 4. Reflow soldering footprint part2 for HVQFN40 (SOT618-16(SC))

HVQFN40, thermal enhanced very thin quad flat package; no leads; step-cut wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HVQFN40 (SOT618-16(SC))

HVQFN40, thermal enhanced very thin quad flat package; no leads; step-cut wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.8 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP SHOULD BE 0.25 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN40 (SOT618-16(SC))

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